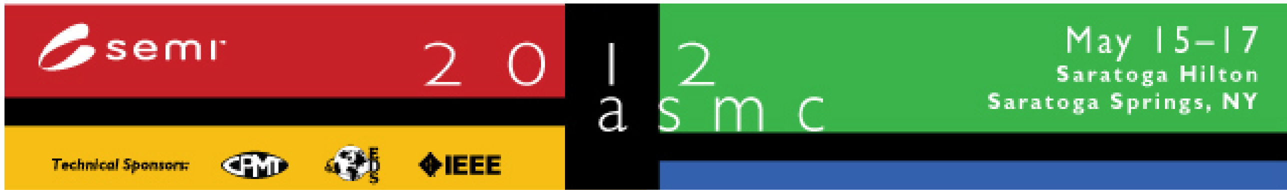

Tuesday, May 15, 2012 (day one)

Session 6 - Advanced Metrology II (in parallel with Session 5)

Chairs: Pat Gabella, The Gabella Group; David Huang, Pall Microelectronics; Thanas Budri, Texas Instruments

Advanced semiconductor manufacturing demands advanced metrology techniques. This session details some new reflectometry, ellipsometry, scatterometry, X-ray and thermal wave use cases.

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3:30

6.1 Scatterometry Measurement for SiGe AEI Sigma-Shaped Gate Structures of 28nm Technology

Yu-Wen Wang, Autumn Yeh, Pao-Chung Lin, Chin-Cheng Chien, United Microelectronics Corporation; Lanny Mihardja, Ching-Hung Bert Lin, Zhi-Qing James Xu, Chao-Yu Harvey Cheng, Sungchul Yoo, Jason Lin, Catherine Perry-Sullivan, KLA-Tencor Corporation

3:55

6.2 In-line Metrology Capability for Epitaxial Multi-stack SiGe Layers

D. Le Cunff, S. Couvrat, F. Abbate, STMicroelectronics

4:20

6.3 Laser Micro-Scale Thermal Wave Characterization of Heat Transport Processes in Modern Semiconductor Structures and Devices

A.L. Glazov, K.L. Muratikov, Ioffe Physical-Technical Institute of RAS; V.A. Kozlov, FID Technology Ltd

4:45

6.4 Development of CMP Pad Using an Unpatterned Surface Inspection System

C.Y. Cheng, S.N. Peng, S.C. Chen, Dow Chemical Co.; Larry Yang, Debbie Hu, Steve Lin, KLA-Tencor Corporation